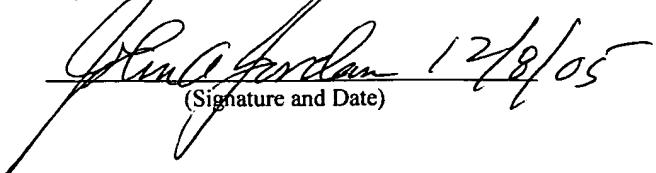


IFW

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, ON December 8, 2005.

Depositor: John A. Jordan

  
(Signature and Date) 12/8/05

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<u>In Re Application of</u>	:	December 8, 2005
<u>John H. Magerlein, et al.</u>	:	Examiner: N/A Confirmation No.: 2811
<u>Serial No.: 10/771,817</u>	:	Art Unit: 3965
<u>Filed: June 16, 2004</u>	:	IBM Corporation Intellectual Property Law Dept.1Q0A/040-3,1701 North Street Endicott, New York 13760
<b>Title: METHOD OF MANUFACTURE OF SILICON BASED PACKAGE AND DEVICES MANUFACTURED THEREBY</b>	:	

**STATUS LETTER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The status of the above-identified application, Serial No. 10/771,817 filed on June 16, 2004, is requested.

Respectfully submitted,

John H. Magerlein, et al.

By:

  
John A. Jordan Attorney  
Registration No. 24,655  
Tel. (518) 587-1902

WHS/JAJ

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